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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/538,505	06/09/2005	Keiichi Murakami	2005-0872A	7088
513	7590	02/06/2009	EXAMINER	
WENDEROTH, LIND & PONACK, L.L.P.			PHAN, THIEM D	
2033 K STREET N. W.			ART UNIT	PAPER NUMBER
SUITE 800			3729	
WASHINGTON, DC 20006-1021				
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		02/06/2009	PAPER	

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Office Action Summary	Application No. 10/538,505	Applicant(s) MURAKAMI, KEIICHI
	Examiner THIEM PHAN	Art Unit 3729

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --
Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If no period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED. (35 U.S.C. § 133).

Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1) Responsive to communication(s) filed on 19 December 2008.

2a) This action is FINAL. 2b) This action is non-final.

3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4) Claim(s) 1-11 is/are pending in the application.

4a) Of the above claim(s) _____ is/are withdrawn from consideration.

5) Claim(s) _____ is/are allowed.

6) Claim(s) 1-11 is/are rejected.

7) Claim(s) _____ is/are objected to.

8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9) The specification is objected to by the Examiner.

10) The drawing(s) filed on 6/09/05 is/are: a) accepted or b) objected to by the Examiner.

Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).

11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).

a) All b) Some * c) None of:

1. Certified copies of the priority documents have been received.
2. Certified copies of the priority documents have been received in Application No. _____.
3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) Notice of References Cited (PTO-892)

2) Notice of Draftsperson's Patent Drawing Review (PTO-948)

3) Information Disclosure Statement(s) (PTO/0250) _____
Paper No(s)/Mail Date 12/19/08.

4) Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____.

5) Notice of Informal Patent Application

6) Other: _____.

DETAILED ACTION

Continued Examination Under 37 CFR 1.114

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicants' submission filed on 12/19/08 has been entered.

Claim Rejections - 35 USC § 112

2. The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

3. Claim 2 is rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention. The claim language "... increased in predetermined steps." is vague and indefinite.

Claim Rejections - 35 USC § 102

4. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless —

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

5. Claims 1-11 are rejected under 35 U.S.C. 102(b) as being anticipated by Keiichi Murakami (JP 2000-332387), hereinafter '387.

Regarding claims 1 and 7, the '387 teaches a method of producing multilayer printed circuit board which includes forming a thermosetting resin layer (Fig. 5, 16) so as to fill spaces between circuit patterns (Fig. 5, 15) formed on a surface of the printed wiring board (Fig. 3, 10), heating and curing the resin layer (Col. 23, lines 52 & 53), and then polishing the cured resin layer covering the circuit patterns, thereby exposing the circuit patterns (Col. 24, lines 1-4), wherein the step of heating and curing the resin layer comprises:

- maintaining the resin layer (Fig. 6, 16; Paragr. 17) at a non-curable temperature where the resin layer is pressed via a smoothing plate (19) in a reduced pressure environment such as low pressure chamber or enclosure;
- heating the resin layer (Paragr. 18) in the pressed state to a curing temperature at which the resin layer is cured;
- introducing outside air into the reduced pressure environment while maintaining the pressed state and the curing temperature, reducing the pressure applied to the smoothing plate while maintaining the curing temperature and cooling the resin layer to remove the smoothing plate (19) for next phase of polishing (Figs. 7 & 8; Paragr. 19);
- wherein a metallic foil with a roughened surface (Fig. 6, 17) facing the resin layer is superposed on the resin layer.

Regarding claim 2, as best understood, the '387 teaches a stepwise applied pressure increase to the smoothing plate (Fig. 6, 17) against the circuit board (11).

Regarding claims 3 and 8, the '387 teaches that the resin layer is formed by adhering a liquid resin (Fig. 6, 16) to the printed wiring board so as to fill spaces between the circuit patterns (15).

Regarding claims 4 and 10, the '387 teaches that the resin layer is formed by superposing a semi-cured resin sheet (Fig. 5, 16; Paragr. 16) on the printed wiring board.

Regarding claims 5, 6, 9 and 11, the '387 teaches that the metallic foil (Fig. 6, 17) is formed with a different type of metal than the circuit patterns (15).

Response to Arguments

6. Applicant's arguments with respect to claims 1-9 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

7. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Tim Phan whose telephone number is 571-272-4568. The examiner can normally be reached on M & Tu, 6AM - 2PM, and W & Th, 9AM – 5PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, David Bryant can be reached on 571-272-4526. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

/Phan Thiem/
Primary Examiner, Art Unit 3729

February 1, 2009